

## Automotive-grade N-channel 100 V, 2.3 mΩ typ., 180 A STripFET™ F7 Power MOSFET in a TO-220 package

Datasheet - production data

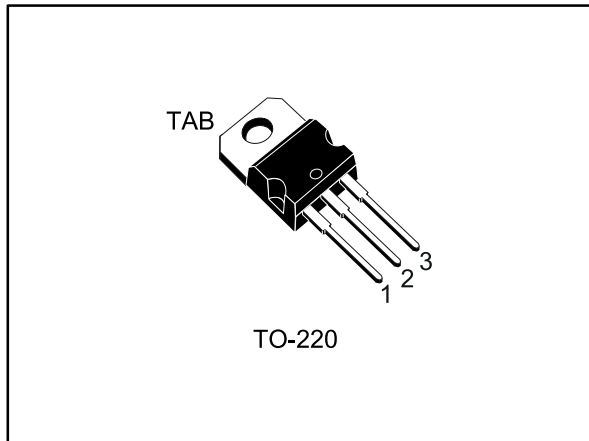
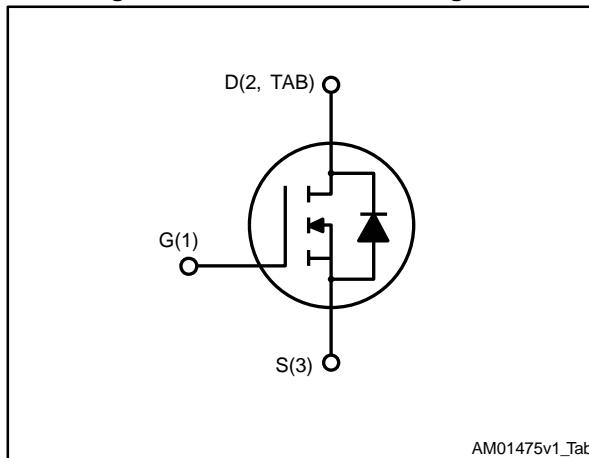


Figure 1: Internal schematic diagram



### Features

Order code	V <sub>DS</sub>	R <sub>DS(on)max</sub>	I <sub>D</sub>
STP315N10F7	100 V	2.7 mΩ	180 A

### Features

- Designed for automotive applications and AEC-Q101 qualified
- Among the lowest R<sub>DS(on)</sub> on the market
- Excellent FoM (figure of merit)
- Low C<sub>rss</sub>/C<sub>iss</sub> ratio for EMI immunity
- High avalanche ruggedness

### Applications

- Switching applications

### Description

This N-channel Power MOSFET utilizes STripFET™ F7 technology with an enhanced trench gate structure that results in very low on-state resistance, while also reducing internal capacitance and gate charge for faster and more efficient switching.

Table 1: Device summary

Order code	Marking	Package	Packaging
STP315N10F7	315N10F7	TO-220	Tube

## Contents

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# 1 Electrical ratings

**Table 2: Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	100	V
$V_{GS}$	Gate-source voltage	$\pm 20$	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	180	A
$I_D^{(1)}$	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	120	A
$I_{DM}^{(2)}$	Drain current (pulsed)	720	A
$P_{TOT}$	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$	315	W
$E_{AS}^{(3)}$	Single pulse avalanche energy ( $T_J = 25\text{ }^\circ\text{C}$ , $L=0.55\text{ mH}$ , $I_{AS}=65\text{ A}$ )	1	J
$T_J$	Operating junction temperature range	-55 to 175	$^\circ\text{C}$
$T_{stg}$	Storage temperature range		

**Notes:**

(1)Current limited by package.

(2)Pulse width limited by safe operating area.

(3)Starting  $T_J=25^\circ\text{C}$ ,  $I_D=60\text{ A}$ ,  $V_{DD}=50\text{ V}$ .

**Table 3: Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	0.48	$^\circ\text{C/W}$
$R_{thj-amb}$	Thermal resistance junction-ambient	62.5	$^\circ\text{C/W}$

## 2 Electrical characteristics

( $T_C = 25\text{ °C}$  unless otherwise specified)

**Table 4: On /off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}$ , $I_D = 250\text{ }\mu\text{A}$	100			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$ , $V_{DS} = 100\text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0\text{ V}$ , $V_{DS} = 100\text{ V}$ , $T_C = 125\text{ °C}$ <sup>(1)</sup>			100	$\mu\text{A}$
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0\text{ V}$ , $V_{GS} = 20\text{ V}$			100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	2.5	3.5	4.5	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$ , $I_D = 60\text{ A}$		2.3	2.7	m $\Omega$

**Notes:**

<sup>(1)</sup>Defined by design, not subject to production test.

**Table 5: Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{GS} = 0\text{ V}$ , $V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$	-	12800	-	pF
$C_{oss}$	Output capacitance		-	3500	-	pF
$C_{riss}$	Reverse transfer capacitance		-	170	-	pF
$Q_g$	Total gate charge	$V_{DD} = 50\text{ V}$ , $I_D = 180\text{ A}$ , $V_{GS} = 10\text{ V}$	-	180	-	nC
$Q_{gs}$	Gate-source charge	(see <a href="#">Figure 14: "Test circuit for gate charge behavior"</a> )	-	78	-	nC
$Q_{gd}$	Gate-drain charge		-	34	-	nC

**Table 6: Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 50\text{ V}$ , $I_D = 90\text{ A}$ , $R_G = 4.7\text{ }\Omega$ , $V_{GS} = 10\text{ V}$ (see <a href="#">Figure 13: "Test circuit for resistive load switching times"</a> and <a href="#">Figure 18: "Switching time waveform"</a> )	-	62	-	ns
$t_r$	Rise time		-	108	-	ns
$t_{d(off)}$	Turn-off delay time		-	148	-	ns
$t_f$	Fall time		-	40	-	ns

Table 7: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		180	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		720	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0\text{ V}$ , $I_{SD} = 60\text{ A}$	-		1.5	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 180\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 80\text{ V}$ , $T_J = 150\text{ }^\circ\text{C}$ (see <a href="#">Figure 15: "Test circuit for inductive load switching and diode recovery times"</a> )	-	85		ns
$Q_{rr}$	Reverse recovery charge		-	200		nC
$I_{RRM}$	Reverse recovery current		-	4.7		A

**Notes:**

(1)Pulse width limited by safe operating area.

(2)Pulse duration = 300 $\mu\text{s}$ , duty cycle 1.5%

## 2.2 Electrical characteristics (curves)

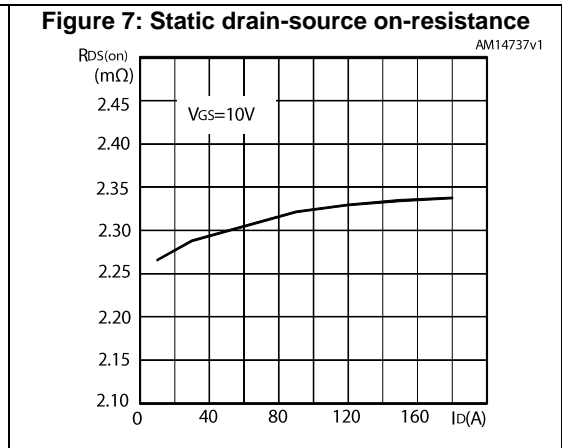
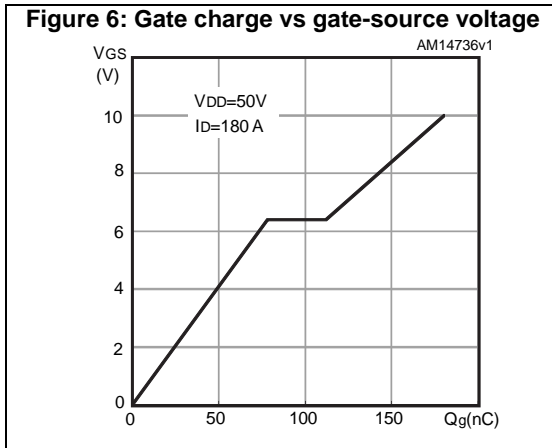
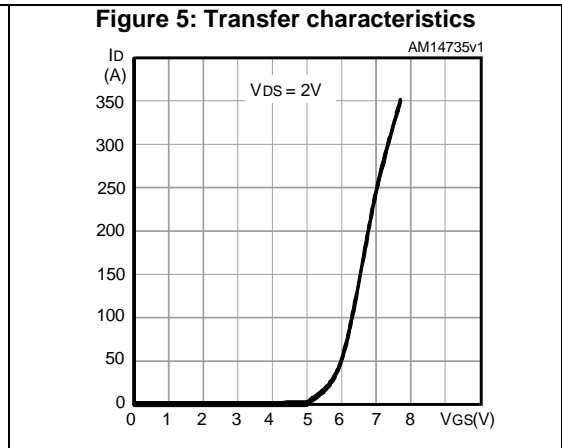
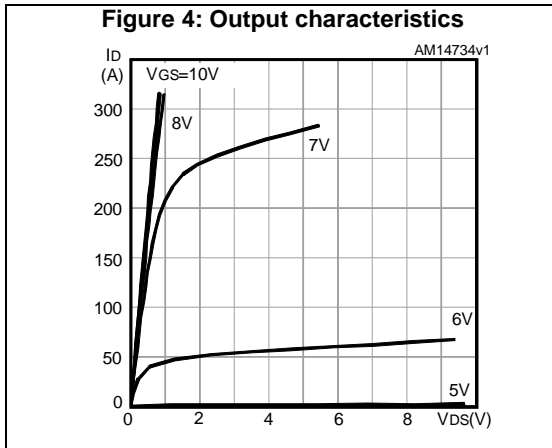
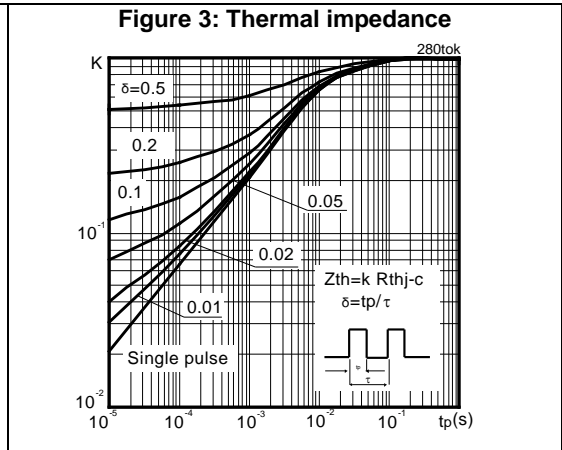
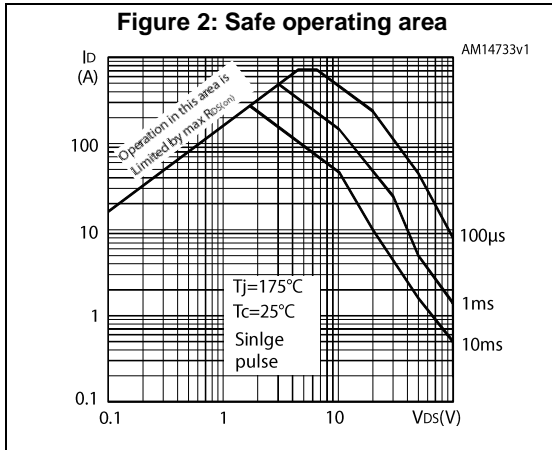


Figure 8: Capacitance variations

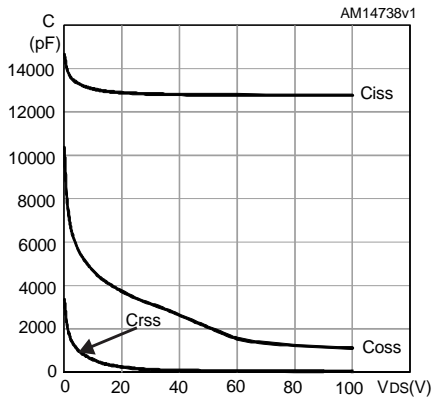


Figure 9: Normalized on-resistance vs temperature

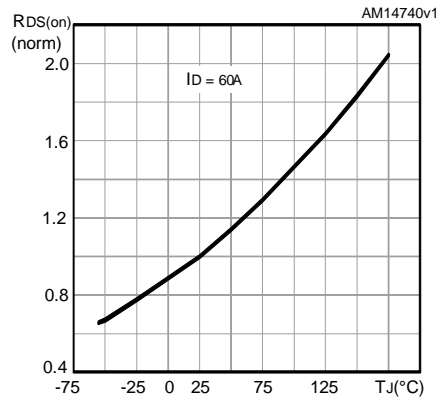


Figure 10: Normalized  $V_{(BR)DSS}$  vs temperature

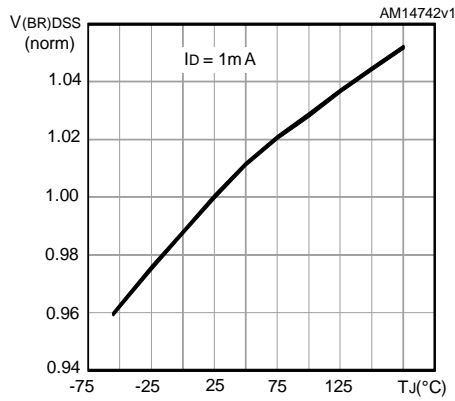


Figure 11: Normalized gate threshold voltage vs temperature

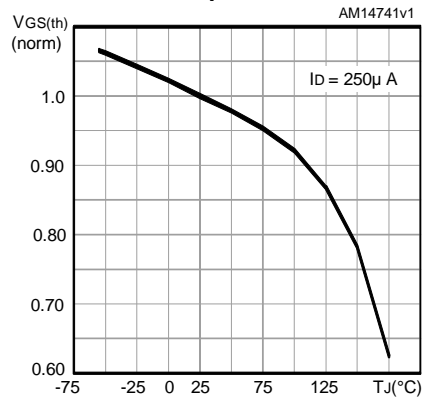
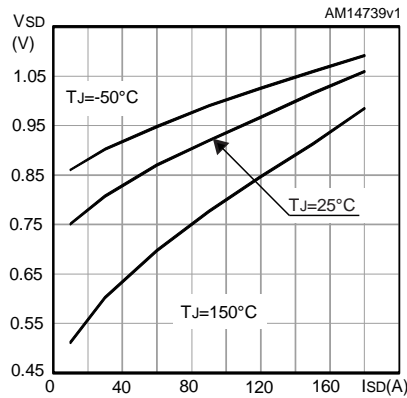


Figure 12: Source-drain diode forward characteristics



### 3 Test circuits

**Figure 13: Test circuit for resistive load switching times**



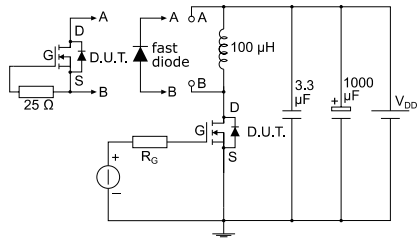
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**Figure 14: Test circuit for gate charge behavior**



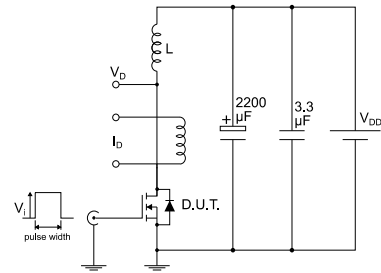
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**Figure 15: Test circuit for inductive load switching and diode recovery times**



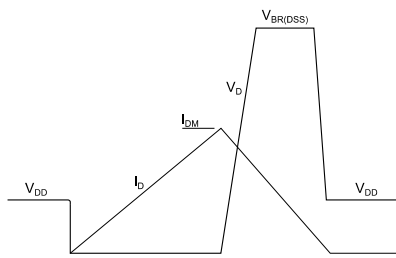
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**Figure 16: Unclamped inductive load test circuit**



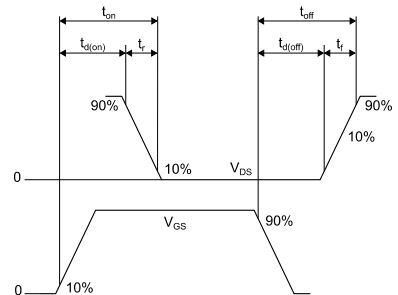
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**Figure 17: Unclamped inductive waveform**



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**Figure 18: Switching time waveform**



AM01473v1



## 4 Package information data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 4.1 TO-220 type A package information

Figure 19: TO-220 type A package outline

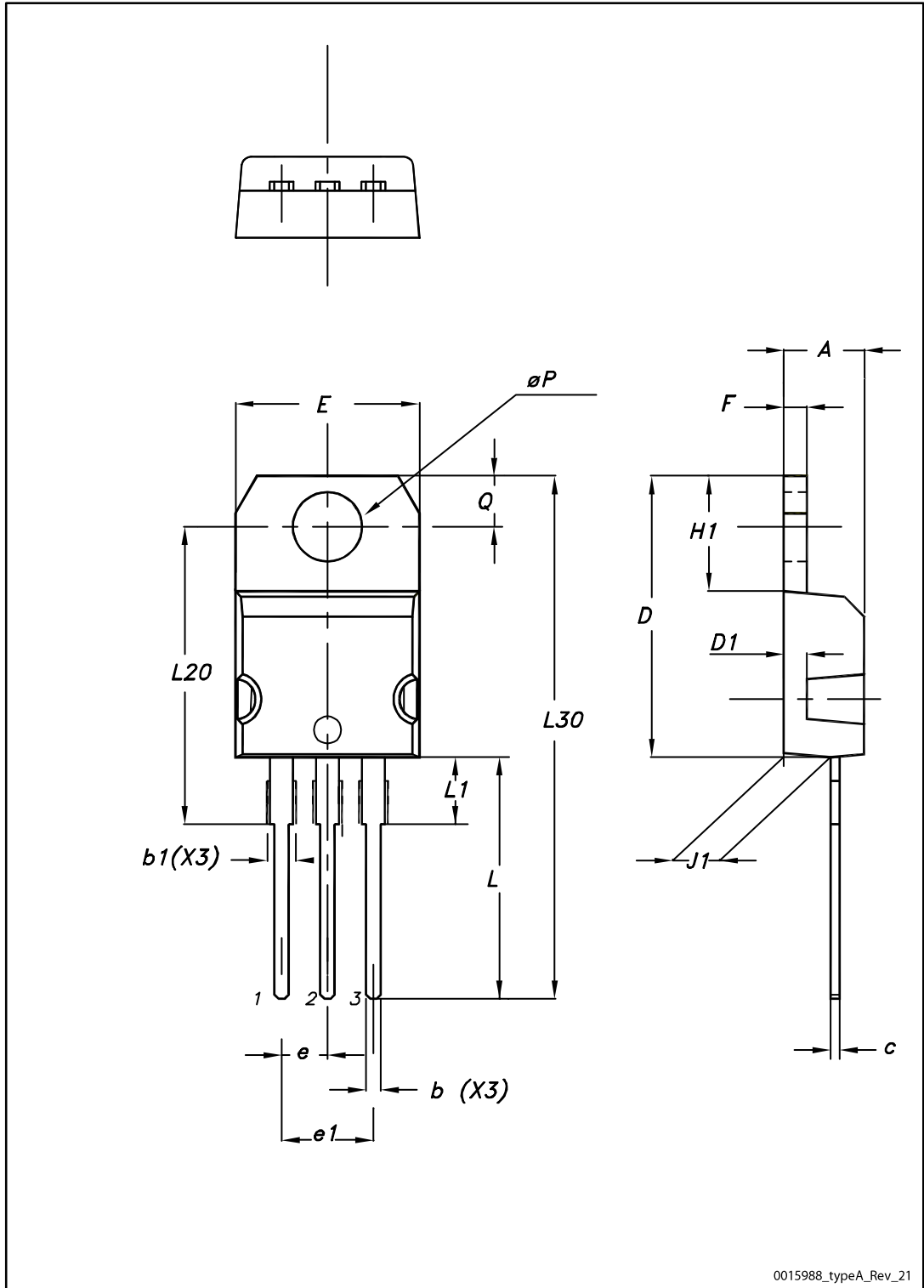


Table 8: TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95

## 5 Revision history

**Table 9: Document revision history**

Date	Revision	Changes
07-Oct-2013	1	First release.
27-May-2014	2	– Modified: title and <i>Features</i> in cover page – Minor text changes
12-Sep-2014	3	– Modified: title, features and description in cover page.
29-Aug-2016	4	Modified: <a href="#">Table 2: "Absolute maximum ratings"</a> and <a href="#">Table 4: "On /off states"</a> Updated: <a href="#">Section 7.1: "TO-220 type A package information"</a> Minor text changes

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